

### • General Description

The AGM3015D combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

### • Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

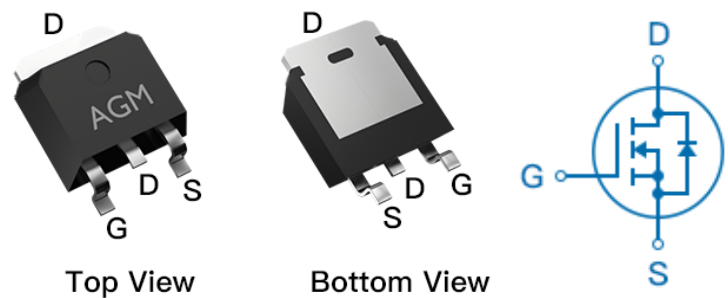
### • Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

BVDSS	RDSON	ID
30V	2mΩ	160A

### TO-252 Pin Configuration



### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM3015D	AGM3015D	TO-252	330mm	16mm	2500

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	30	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) <b>(Note 1)</b>	160	A
	Drain Current-Continuous(Tc=100°C)	105	A
IDM (pulse)	Drain Current-Pulsed <b>(Note 2)</b>	650	A
PD	Maximum Power Dissipation(Tc=25°C)	130	w
	Maximum Power Dissipation(Tc=100°C)	52	w
EAS	Avalanche energy <b>(Note 3)</b>	756	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	50	°C/W
RθJC	Thermal Resistance Junction-Case <sup>1</sup>	---	0.96	°C/W

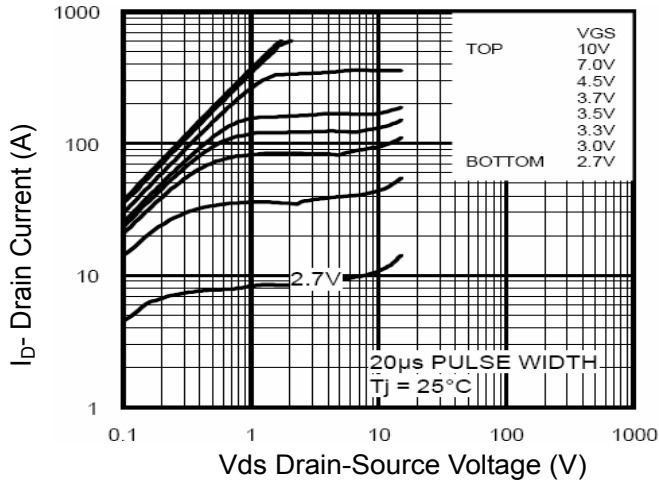
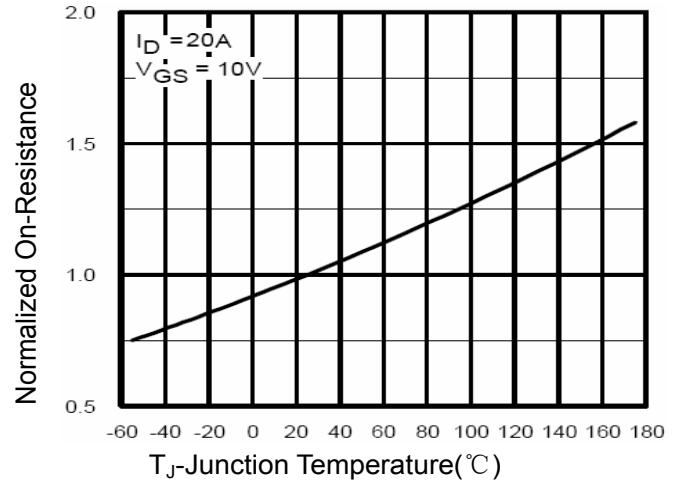
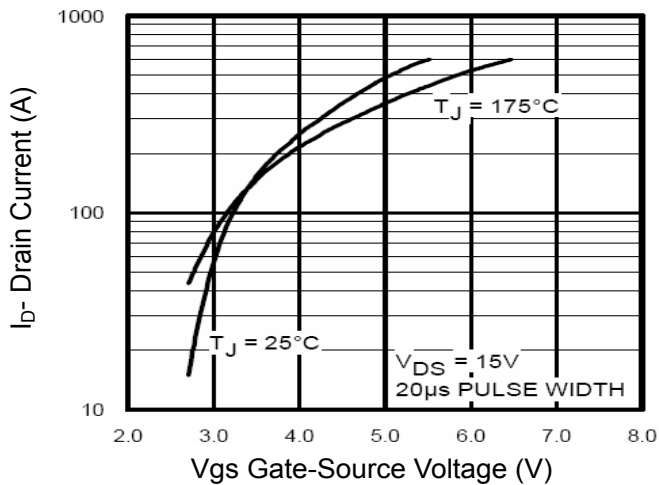
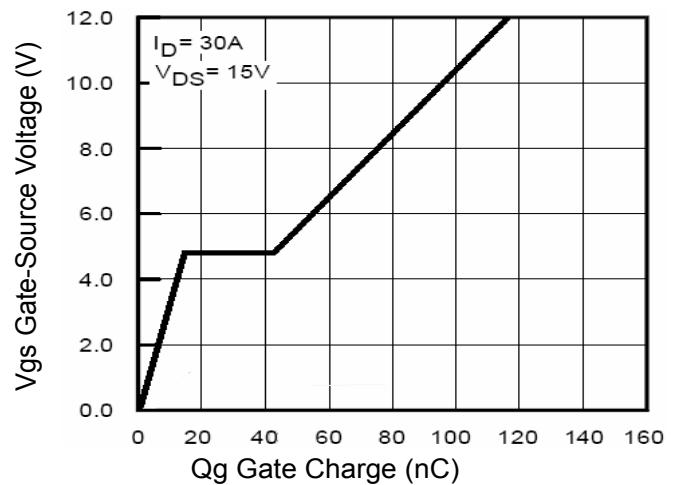
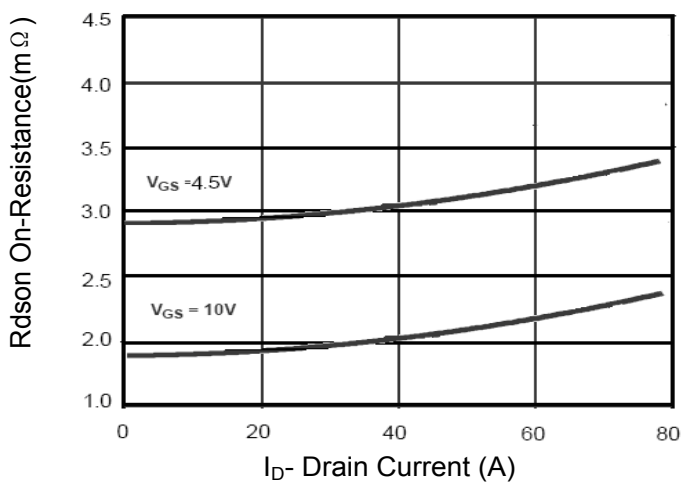
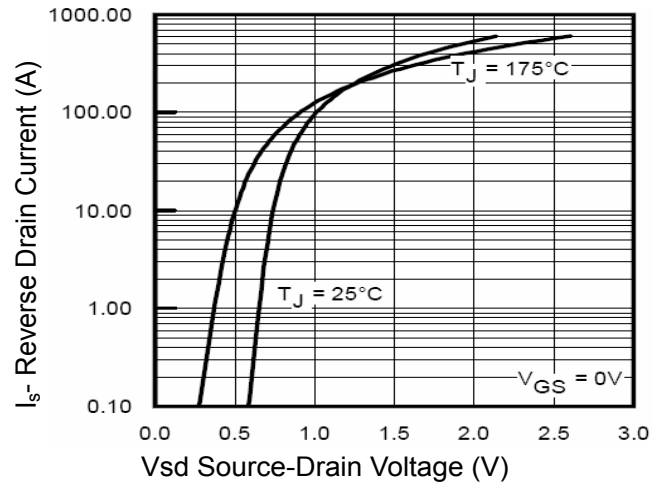
**Table 3. Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=30V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.2	1.5	2.2	V
gFS	Forward Transconductance	VDS=5V, ID=15A	--	36	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A	--	2.0	2.3	mΩ
		VGS=4.5V, ID=15A	--	3.1	4.0	mΩ
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=15V, VGS=0V, F=1MHZ	--	5600	--	pF
Coss	Output Capacitance		--	800	--	pF
Crss	Reverse Transfer Capacitance		--	560	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V, f=1.0MHz	--	1.6	--	Ω
<b>Switching Times</b>						
td(on)	Turn-on Delay Time	VGS=10V, VDS=15V, ID=10A, RGEN=6Ω	--	25	--	nS
tr	Turn-on Rise Time		--	23	--	nS
td(off)	Turn-Off Delay Time		--	90	--	nS
tf	Turn-Off Fall Time		--	39	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=15V, ID=12A	--	99	--	nC
Qgs	Gate-Source Charge		--	17	--	nC
Qgd	Gate-Drain Charge		--	11	--	nC
<b>Source-Drain Diode Characteristics</b>						
ISD	Source-Drain Current(Body Diode)		--	--	160	A
VSD	Forward on Voltage	VGS=0V, IS=20A	--	--	1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs , TJ=25°C	--	39	--	ns
Qrr	Reverse Recovery Charge		--	35	--	nc

Notes 1. The maximum current rating is package limited.

Notes 2. Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3. EAS condition: T<sub>J</sub>=25°C, V<sub>gs</sub>=10V, V<sub>dd</sub>=20V, I<sub>D</sub>=55A, L=0.5mH, R<sub>g</sub>=25ohm

**Typical Electrical and Thermal Characteristics (Curves)**

**Figure 1 Output Characteristics**

**Figure 4 Rdson-Junction Temperature**

**Figure 2 Transfer Characteristics**

**Figure 5 Gate Charge**

**Figure 3 Rdson- Drain Current**

**Figure 6 Source- Drain Diode Forward**

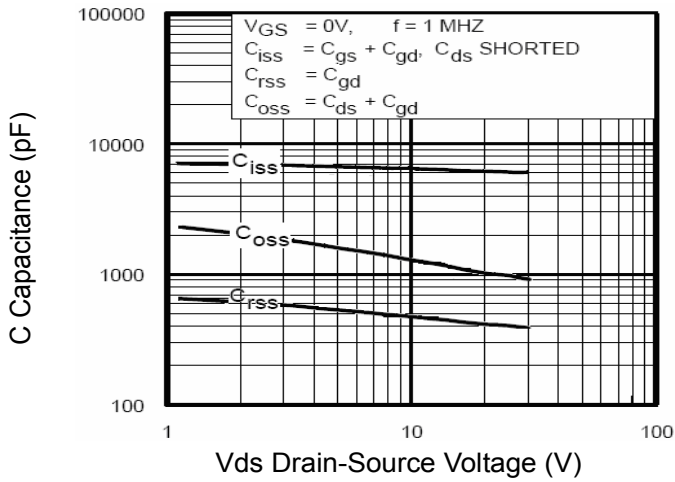


Figure 7 Capacitance vs Vds

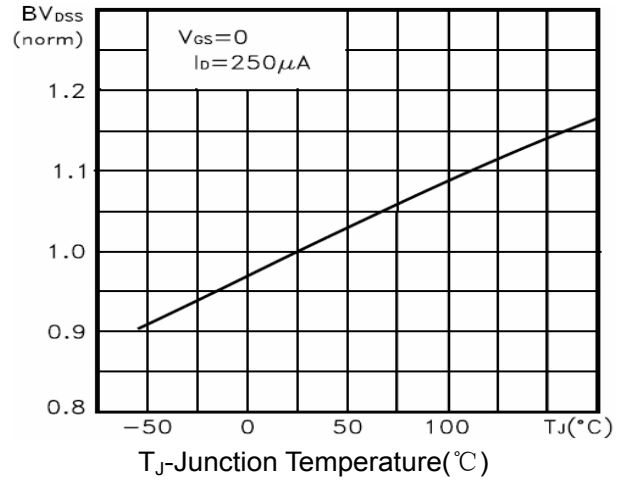


Figure 9  $BV_{DSS}$  vs Junction Temperature

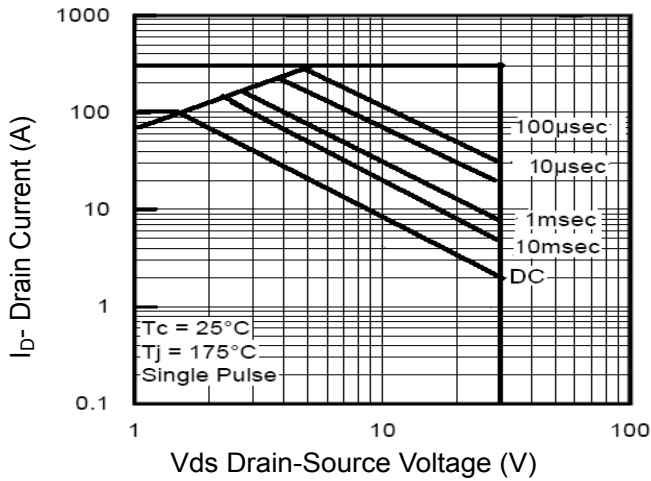


Figure 8 Safe Operation Area

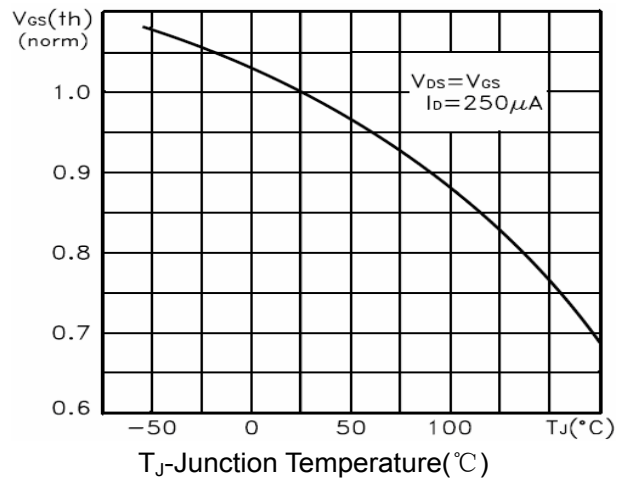


Figure 10  $V_{GS(th)}$  vs Junction Temperature

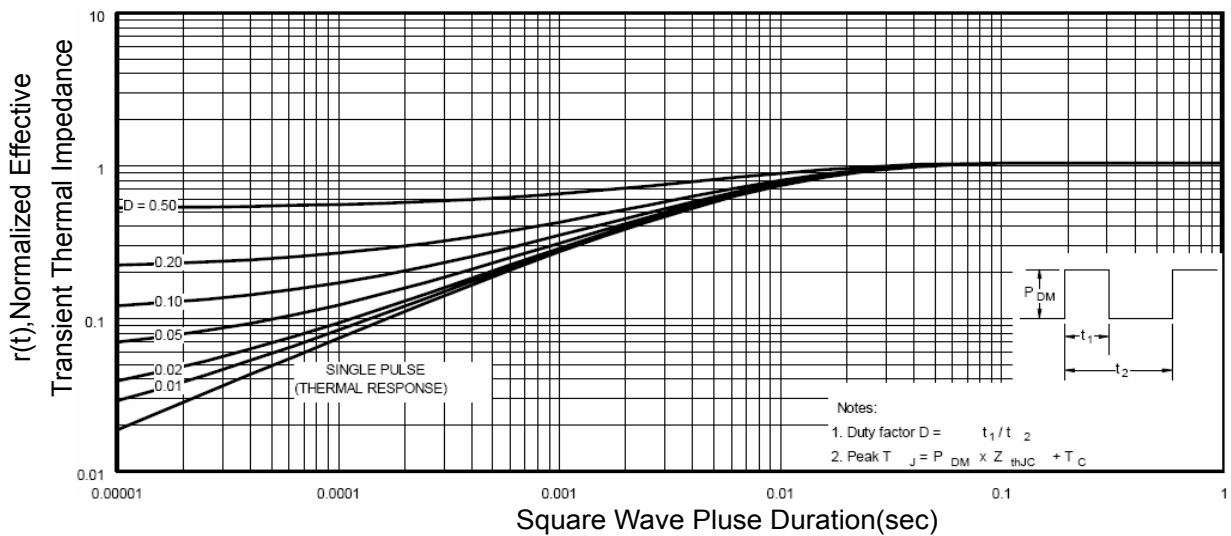
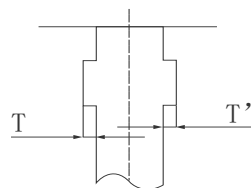
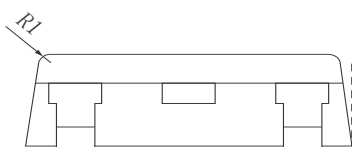
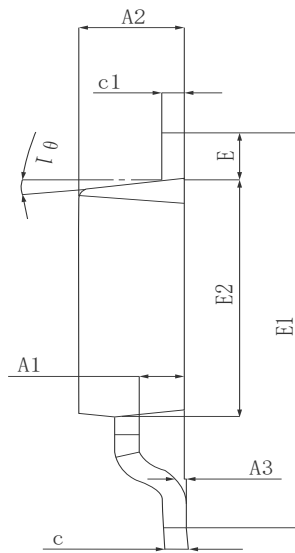
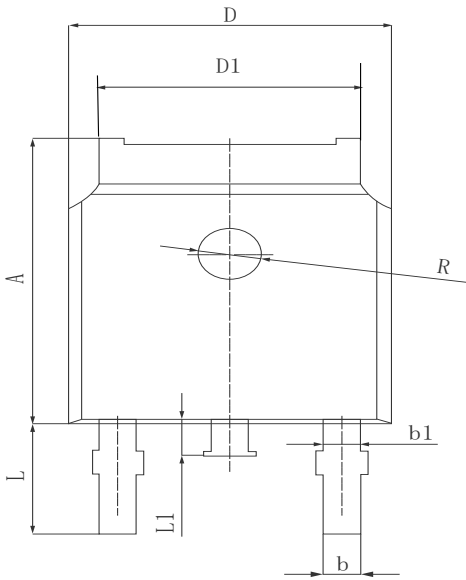
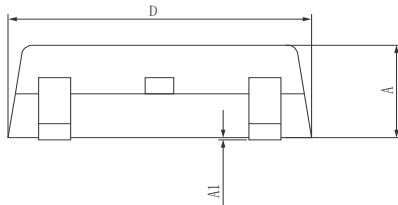
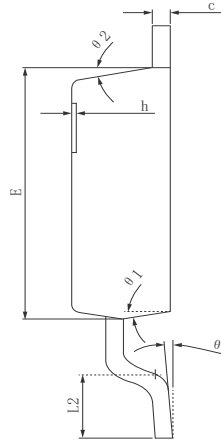
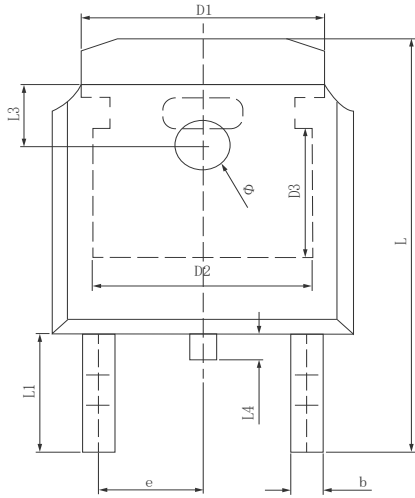


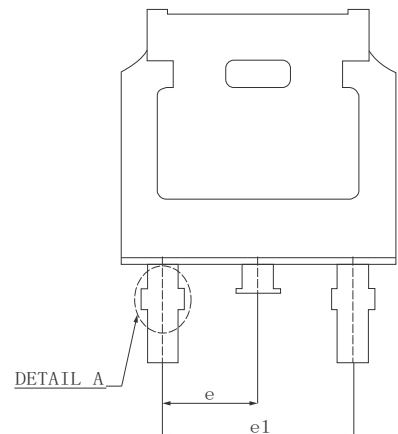
Figure 11 Normalized Maximum Transient Thermal Impedance

**●Dimensions (TO-252)**


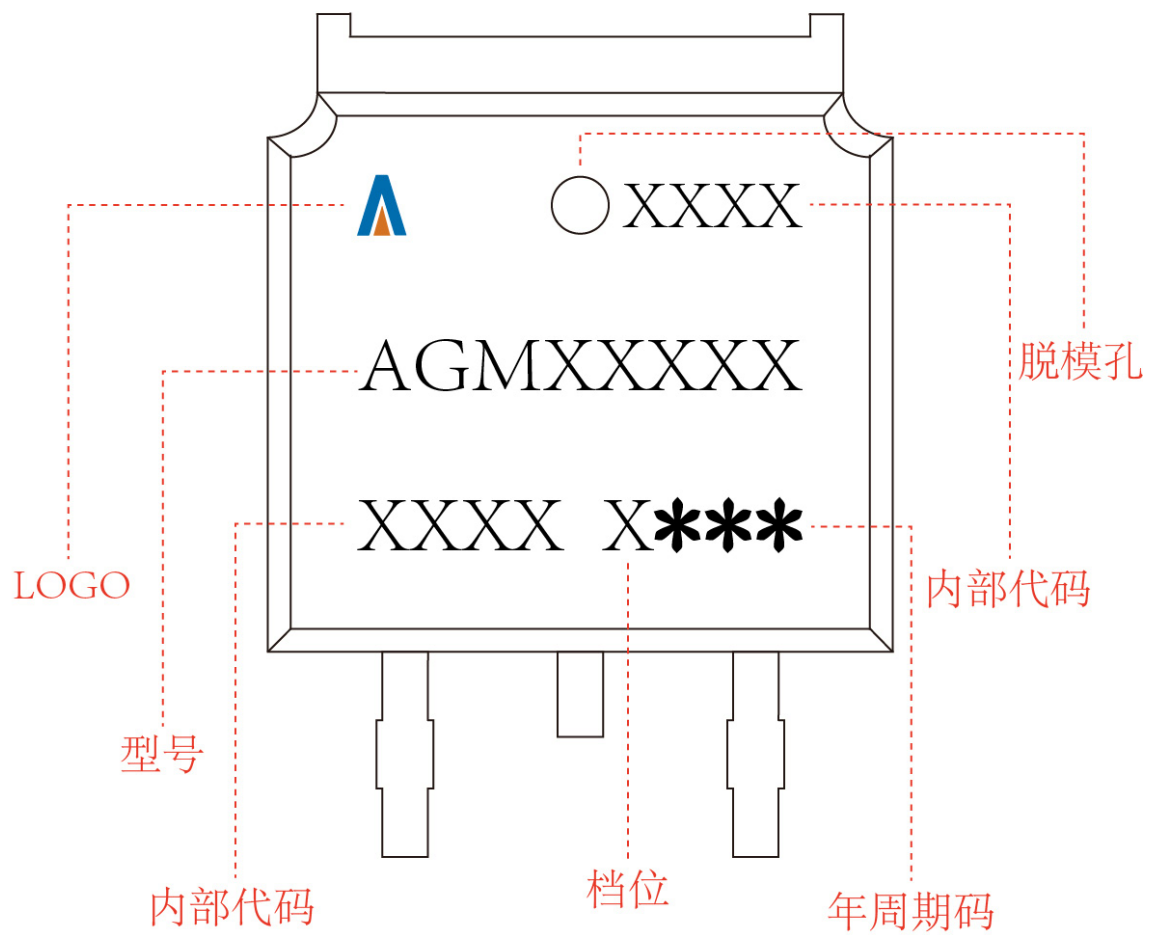
$0 \leq T, T' \leq 0.12$   
**DETAIL A**

SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ 1	9° TYP		
θ 2	9° TYP		

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	7.050	7.100	7.150
A1	0.960	1.010	1.060
A2	2.250	2.300	2.350
A3	0.000	0.050	0.100
b	0.760REF.		
b1	1.000REF.		
c	0.508REF.		
c1	0.508REF.		
D	6.550	6.600	6.650
D1	5.220	5.320	5.420
E	0.950	1.000	1.050
E1	9.700	9.900	10.100
E2	6.050	6.100	6.150
e	2.286BSC		
e1	4.572REF.		
L	2.650	2.800	2.950
L1	0.700	0.800	0.900
θ 1	7° REF.		
R	1.300REF.		
R1	0.250REF.		



TO-252  
Marking Instructions:




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